

<b>PCN Number:</b>	20190725001.1		<b>PCN Date:</b>	Jul 29, 2019	
<b>Title:</b>	Qualification of additional Fab site (DMOS6) and Assembly site (JCAP) options for select devices				
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>		<b>Dept:</b>	Quality Services	
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Oct 29, 2019		<b>Estimated Sample Availability:</b>	Date provided at sample request.	
<b>Change Type:</b>					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		
<b>PCN Details</b>					
<b>Description of Change:</b>					
Texas Instruments is pleased to announce the qualification of an additional fab (DMOS6) and assembly (JCAP) site for selected devices as listed below in the product affected section.					
<b>Current Fab Site</b>			<b>Additional Fab Site</b>		
<b>Current Fab Site</b>	<b>Process</b>	<b>Wafer Diameter</b>	<b>Additional Fab Site</b>	<b>Process</b>	<b>Wafer Diameter</b>
RFAB	LBC8	300 mm	DMOS6	LBC8	300 mm
There are no material difference between devices currently manufactured and devices built with this manufacturing option.					
<b>Reason for Change:</b>					
Continuity of Supply					
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>					
None					
<b>Anticipated impact on Material Declaration</b>					
<input checked="" type="checkbox"/>	No Impact to the Material Declaration	<input type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <a href="#">TI ECO website</a> .		
<b>Changes to product identification resulting from this PCN:</b>					
<b>Fab Site Information:</b>					
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City		
RFAB	RFB	USA	Richardson		
<b>DMOS6</b>	<b>DM6</b>	<b>USA</b>	<b>Dallas</b>		
<b>Assembly Site Information:</b>					
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City		
TI Clark	QAB	PHL	Angeles City, Pampanga		
<b>JCAP</b>	<b>JCP</b>	<b>CHN</b>	<b>Jiangyin</b>		

Sample product shipping label (not actual product label)

**TEXAS INSTRUMENTS**  
 MADE IN: China  
 2DC: 2Q  
 MSL 1 /260C/UNLIM SEAL DT  
 04/14/17  
 OPT: 73  
 ITEM: 73  
 LBL: 1A (L)T0:1168  
 (1P) PTAS2560YFFR  
 (Q) 3000 (D) 1710  
 (31T) LOT: 7133710JCP  
 (4W) SWR (1T) 2855550Z9A  
 (P)  
 (2P) REV: A0 (V) 0033317  
 (20L) CSO: DM6 (21L) CCO: USA  
 (22L) ASO: JCP (23L) ACO: CHN

**Product Affected:**

AFE4410YZR	AFE4410YZT
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**Qualification Report**

Approve Date 17-Jul-2019

**Qualification Results**

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: AFE4410YZR	QBS Product Reference: AFE4900YZR	QBS Process Reference: TAS2552YFF	QBS Process Reference: TAS2553YFF	QBS Package Reference: LM3566YFFR	QBS Package Reference: SN2025YFF
CDM	ESD - CDM	1000 V	1/3/0	1/3/0	-	-	-	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	1/Pass	-	3/Pass	3/90/0	-
ED	Incremental Electrical Char.	Full Temp & Voltage range	-	-	-	-	-	1/Pass
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	-	3/3000/0	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	-	3/229/0	2/154/0
HBM	ESD - HBM	1000 V	1/3/0	-	-	-	-	-
HTOL	Life Test, 125C	1000 Hours	-	-	-	3/231/0	6/329/0	-
HTOL	Life Test, 125C	500	1/80/0	1/80/0	-	-	-	-
HTSL	High Temp Storage Bake 170C	420 Hours	-	1/77/0	3/228/0	-	3/165/0	1/45/0
LU	Latch-up	(Per JESD78)	1/6/0	1/6/0	-	3/18/0	4/24/0	-
PD	Physical Dimensions	(per mechanical drawing)	-	-	-	-	-	1/10/0
SBS	Bump Shear	Solder Bumps	-	-	3/108/0	-	-	-
SBS	Bump-shear	Per assembly site spec	-	-	-	-	-	1/Pass
TC	Temperature Cycle, -55/125C	700 Cycles	-	1/78/0	3/231/0	-	-	1/77/0
TC	Temperature Cycle, -65/150C	500/Cycles - -65C/150C	-	-	-	-	3/240/0	-

Type	Test Name / Condition	Duration	Qual Device: AFE4410YZR	QBS Product Reference: AFE4900YZR	QBS Process Reference: TAS2552YFF	QBS Process Reference: TAS2553YFF	QBS Package Reference: LM3568YFFR	QBS Package Reference: SN2025YFF
UHAST	Unbiased HAST 110C/85%RH	264	-	1/77/0	-	-	-	-
UHAST	Unbiased HAST 130C/85%RH	96 Hours	-	-	3/228/0	-	3/239/0	1/77/0

- QBS: Qual By Similarity

- Qual Device SN1712025YZR is qualified at LEVEL1-260C

- Qual Device AFE4900YZR is qualified at LEVEL1-260C

- Qual Device AFE4410YZR is qualified at LEVEL1-260C

- Qual Device SN1605049YZR is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

**Green/Pb-free Status:**

Qualified Pb-Free (SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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